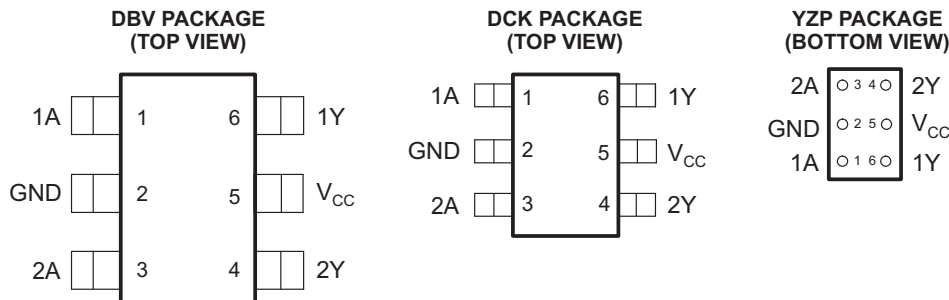


## FEATURES

- Available in the Texas Instruments NanoFree™ Package
- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- Sub-1-V Operable
- Unbuffered Outputs
- Max  $t_{pd}$  of 1.9 ns at 1.8 V
- Low Power Consumption, 10  $\mu$ A at 1.8 V
- $\pm 8$ -mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



See mechanical drawings for dimensions.

## DESCRIPTION/ORDERING INFORMATION

This dual inverter is operational at 0.8-V to 2.7-V  $V_{CC}$ , but is designed specifically for 1.65-V to 1.95-V  $V_{CC}$  operation.

The SN74AUC2GU04 contains two inverters with unbuffered outputs and performs the Boolean function  $Y = \bar{A}$ .

NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

For more information about AUC Little Logic devices, please refer to the TI application report, *Applications of Texas Instruments AUC Sub-1-V Little Logic Devices*, literature number SCEA027.

## ORDERING INFORMATION

| $T_A$         | PACKAGE <sup>(1)</sup>                                            |              | ORDERABLE PART NUMBER | TOP-SIDE MARKING <sup>(2)</sup> |
|---------------|-------------------------------------------------------------------|--------------|-----------------------|---------------------------------|
| –40°C to 85°C | NanoFree™ – WCSP (DSBGA)<br>0.23-mm Large Bump – YZP<br>(Pb-free) | Reel of 3000 | SN74AUC2GU04YZPR      | _ _ _UD_                        |
|               | SOT (SOT-23) – DBV                                                | Reel of 3000 | SN74AUC2GU04DBVR      | UU4_                            |
|               | SOT (SC-70) – DCK                                                 | Reel of 3000 | SN74AUC2GU04DCKR      | UD_                             |

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

(2) DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site.  
YZP: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site. Pin 1 identifier indicates solder-bump composition (1 = SnPb, • = Pb-free).



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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# SN74AUC2GU04

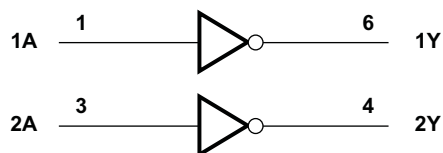
## DUAL INVERTER GATE

SCES438C – APRIL 2003 – REVISED JANUARY 2007

**FUNCTION TABLE  
(EACH INVERTER)**

| INPUT<br>A | OUTPUT<br>Y |
|------------|-------------|
| H          | L           |
| L          | H           |

**LOGIC DIAGRAM (POSITIVE LOGIC)**



### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

|                                                   |                                          |                    | MIN         | MAX                   | UNIT |      |
|---------------------------------------------------|------------------------------------------|--------------------|-------------|-----------------------|------|------|
| V <sub>CC</sub>                                   | Supply voltage range                     |                    | −0.5        | 3.6                   | V    |      |
| V <sub>I</sub>                                    | Input voltage range <sup>(2)</sup>       |                    | −0.5        | 3.6                   | V    |      |
| V <sub>O</sub>                                    | Output voltage range <sup>(2)</sup>      |                    | −0.5        | V <sub>CC</sub> + 0.5 | V    |      |
| I <sub>IK</sub>                                   | Input clamp current                      | V <sub>I</sub> < 0 | −50         |                       | mA   |      |
| I <sub>OK</sub>                                   | Output clamp current                     | V <sub>O</sub> < 0 | −50         |                       | mA   |      |
| I <sub>O</sub>                                    | Continuous output current                |                    | ±20         |                       | mA   |      |
| Continuous current through V <sub>CC</sub> or GND |                                          |                    | ±100        |                       | mA   |      |
| θ <sub>JA</sub>                                   | Package thermal impedance <sup>(3)</sup> |                    | DBV package |                       | 165  | °C/W |
|                                                   |                                          |                    | DCK package |                       | 259  |      |
|                                                   |                                          |                    | YZP package |                       | 123  |      |
| T <sub>std</sub>                                  | Storage temperature range                |                    | −65         | 150                   | °C   |      |

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

## Recommended Operating Conditions<sup>(1)</sup>

|                 |                                    |                          | MIN                    | MAX                    | UNIT |
|-----------------|------------------------------------|--------------------------|------------------------|------------------------|------|
| V <sub>CC</sub> | Supply voltage                     |                          | 0.8                    | 2.7                    | V    |
| V <sub>IH</sub> | High-level input voltage           | I <sub>O</sub> = –100 µA | 0.65 × V <sub>CC</sub> |                        | V    |
| V <sub>IL</sub> | Low-level input voltage            | I <sub>O</sub> = –100 µA |                        | 0.35 × V <sub>CC</sub> | V    |
| V <sub>I</sub>  | Input voltage                      |                          | 0                      | 3.6                    | V    |
| V <sub>O</sub>  | Output voltage                     |                          | 0                      | V <sub>CC</sub>        | V    |
| I <sub>OH</sub> | High-level output current          | V <sub>CC</sub> = 0.8 V  |                        | –0.7                   | mA   |
|                 |                                    | V <sub>CC</sub> = 1.1 V  |                        | –3                     |      |
|                 |                                    | V <sub>CC</sub> = 1.4 V  |                        | –5                     |      |
|                 |                                    | V <sub>CC</sub> = 1.65 V |                        | –8                     |      |
|                 |                                    | V <sub>CC</sub> = 2.3 V  |                        | –9                     |      |
| I <sub>OL</sub> | Low-level output current           | V <sub>CC</sub> = 0.8 V  |                        | 0.7                    | mA   |
|                 |                                    | V <sub>CC</sub> = 1.1 V  |                        | 3                      |      |
|                 |                                    | V <sub>CC</sub> = 1.4 V  |                        | 5                      |      |
|                 |                                    | V <sub>CC</sub> = 1.65 V |                        | 8                      |      |
|                 |                                    | V <sub>CC</sub> = 2.3 V  |                        | 9                      |      |
| Δt/Δv           | Input transition rise or fall rate |                          |                        | 20                     | ns/V |
| T <sub>A</sub>  | Operating free-air temperature     |                          | –40                    | 85                     | °C   |

(1) All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER       | TEST CONDITIONS           | V <sub>CC</sub>                                             | MIN            | TYP <sup>(1)</sup>    | MAX  | UNIT |
|-----------------|---------------------------|-------------------------------------------------------------|----------------|-----------------------|------|------|
| V <sub>OH</sub> | I <sub>OH</sub> = –100 µA | V <sub>IL</sub> = GND                                       | 0.8 V to 2.7 V | V <sub>CC</sub> – 0.1 |      | V    |
|                 | I <sub>OH</sub> = –0.7 mA |                                                             | 0.8 V          | 0.55                  |      |      |
|                 | I <sub>OH</sub> = –3 mA   |                                                             | 1.1 V          | 0.8                   |      |      |
|                 | I <sub>OH</sub> = –5 mA   |                                                             | 1.4 V          | 1                     |      |      |
|                 | I <sub>OH</sub> = –8 mA   |                                                             | 1.65 V         | 1.2                   |      |      |
|                 | I <sub>OH</sub> = –9 mA   |                                                             | 2.3 V          | 1.8                   |      |      |
| V <sub>OL</sub> | I <sub>OL</sub> = 100 µA  | V <sub>IH</sub> = V <sub>CC</sub>                           | 0.8 V to 2.7 V |                       | 0.2  | V    |
|                 | I <sub>OL</sub> = 0.7 mA  |                                                             | 0.8 V          | 0.25                  |      |      |
|                 | I <sub>OL</sub> = 3 mA    |                                                             | 1.1 V          |                       | 0.3  |      |
|                 | I <sub>OL</sub> = 5 mA    |                                                             | 1.4 V          |                       | 0.4  |      |
|                 | I <sub>OL</sub> = 8 mA    |                                                             | 1.65 V         |                       | 0.45 |      |
|                 | I <sub>OL</sub> = 9 mA    |                                                             | 2.3 V          |                       | 0.6  |      |
| I <sub>I</sub>  | A inputs                  | V <sub>I</sub> = V <sub>CC</sub> or GND                     | 0 to 2.7 V     |                       | ±5   | µA   |
| I <sub>CC</sub> |                           | V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0 | 0.8 V to 2.7 V |                       | 10   | µA   |
| C <sub>I</sub>  |                           | V <sub>I</sub> = V <sub>CC</sub> or GND                     | 2.5 V          | 2.5                   |      | pF   |

(1) All typical values are at T<sub>A</sub> = 25°C.

# SN74AUC2GU04

## DUAL INVERTER GATE

SCES438C – APRIL 2003 – REVISED JANUARY 2007

### Switching Characteristics

over recommended operating free-air temperature range,  $C_L = 15$  pF (unless otherwise noted) (see [Figure 1](#))

| PARAMETER       | FROM<br>(INPUT) | TO<br>(OUTPUT) | V <sub>CC</sub> = 0.8 V | V <sub>CC</sub> = 1.2 V<br>± 0.1 V |     | V <sub>CC</sub> = 1.5 V<br>± 0.1 V |     | V <sub>CC</sub> = 1.8 V<br>± 0.15 V |     |     | V <sub>CC</sub> = 2.5 V<br>± 0.2 V |     | UNIT |
|-----------------|-----------------|----------------|-------------------------|------------------------------------|-----|------------------------------------|-----|-------------------------------------|-----|-----|------------------------------------|-----|------|
|                 |                 |                | TYP                     | MIN                                | MAX | MIN                                | MAX | MIN                                 | TYP | MAX | MIN                                | MAX |      |
| t <sub>pd</sub> | A               | Y              | 6.2                     | 0.7                                | 3.1 | 0.7                                | 2.2 | 0.6                                 | 1.1 | 1.9 | 0.5                                | 1.4 | ns   |

### Switching Characteristics

over recommended operating free-air temperature range,  $C_L = 30$  pF (unless otherwise noted) (see [Figure 1](#))

| PARAMETER | FROM<br>(INPUT) | TO<br>(OUTPUT) | $V_{CC} = 1.8$ V<br>$\pm 0.15$ V |     |     | $V_{CC} = 2.5$ V<br>$\pm 0.2$ V |     | UNIT |
|-----------|-----------------|----------------|----------------------------------|-----|-----|---------------------------------|-----|------|
|           |                 |                | MIN                              | TYP | MAX | MIN                             | MAX |      |
| $t_{pd}$  | A               | Y              | 0.7                              | 1.6 | 2.7 | 0.5                             | 2   | ns   |

### Operating Characteristics

$T_A = 25^\circ\text{C}$

| PARAMETER                              | TEST<br>CONDITIONS | $V_{CC} = 0.8$ V | $V_{CC} = 1.2$ V | $V_{CC} = 1.5$ V | $V_{CC} = 1.8$ V | $V_{CC} = 2.5$ V | UNIT |
|----------------------------------------|--------------------|------------------|------------------|------------------|------------------|------------------|------|
|                                        |                    | TYP              | TYP              | TYP              | TYP              | TYP              |      |
| $C_{pd}$ Power dissipation capacitance | f = 10 MHz         | 4.5              | 4.5              | 4.5              | 4.5              | 5.5              | pF   |

## PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10$  MHz,  $Z_o = 50 \Omega$ , slew rate  $\geq 1$  V/ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

## PACKAGING INFORMATION

| Orderable Device | Status<br>(1) | Package Type | Package<br>Drawing | Pins | Package<br>Qty | Eco Plan<br>(2)            | Lead/Ball Finish<br>(6) | MSL Peak Temp<br>(3) | Op Temp (°C) | Device Marking<br>(4/5) | Samples                 |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| 74AUC2GU04DBVRG4 | ACTIVE        | SOT-23       | DBV                | 6    | 3000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | UU4R                    | <a href="#">Samples</a> |
| SN74AUC2GU04DBVR | ACTIVE        | SOT-23       | DBV                | 6    | 3000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | UU4R                    | <a href="#">Samples</a> |
| SN74AUC2GU04DCKR | ACTIVE        | SC70         | DCK                | 6    | 3000           | Green (RoHS<br>& no Sb/Br) | CU NIPDAU               | Level-1-260C-UNLIM   | -40 to 85    | UDR                     | <a href="#">Samples</a> |

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**TAPE AND REEL INFORMATION**


\*All dimensions are nominal

| Device           | Package Type | Package Drawing | Pins | SPQ  | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74AUC2GU04DBVR | SOT-23       | DBV             | 6    | 3000 | 180.0              | 8.4                | 3.23    | 3.17    | 1.37    | 4.0     | 8.0    | Q3            |
| SN74AUC2GU04DCKR | SC70         | DCK             | 6    | 3000 | 180.0              | 8.4                | 2.41    | 2.41    | 1.2     | 4.0     | 8.0    | Q3            |

## TAPE AND REEL BOX DIMENSIONS

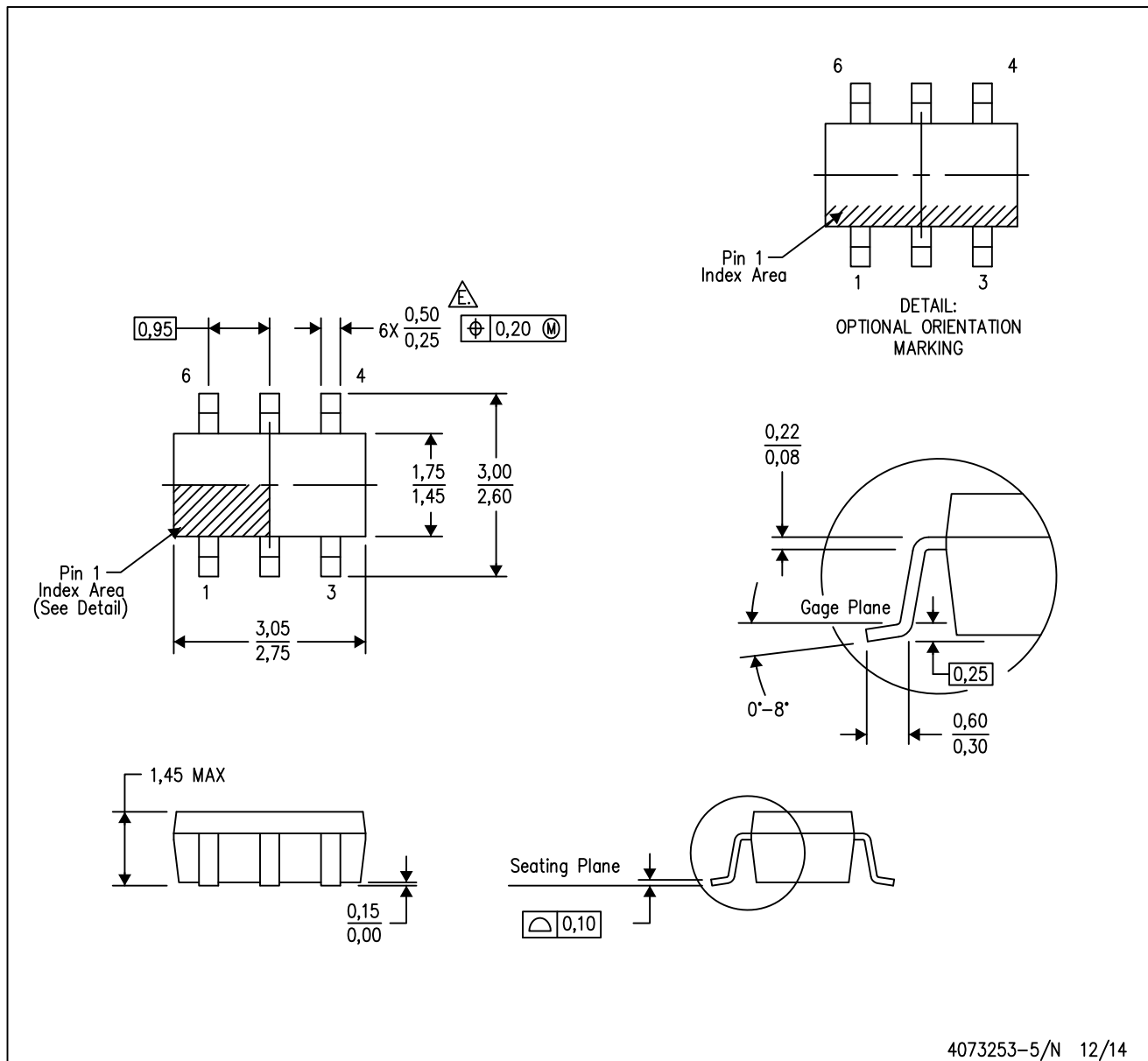


\*All dimensions are nominal

| Device           | Package Type | Package Drawing | Pins | SPQ  | Length (mm) | Width (mm) | Height (mm) |
|------------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74AUC2GU04DBVR | SOT-23       | DBV             | 6    | 3000 | 202.0       | 201.0      | 28.0        |
| SN74AUC2GU04DCKR | SC70         | DCK             | 6    | 3000 | 202.0       | 201.0      | 28.0        |

DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE

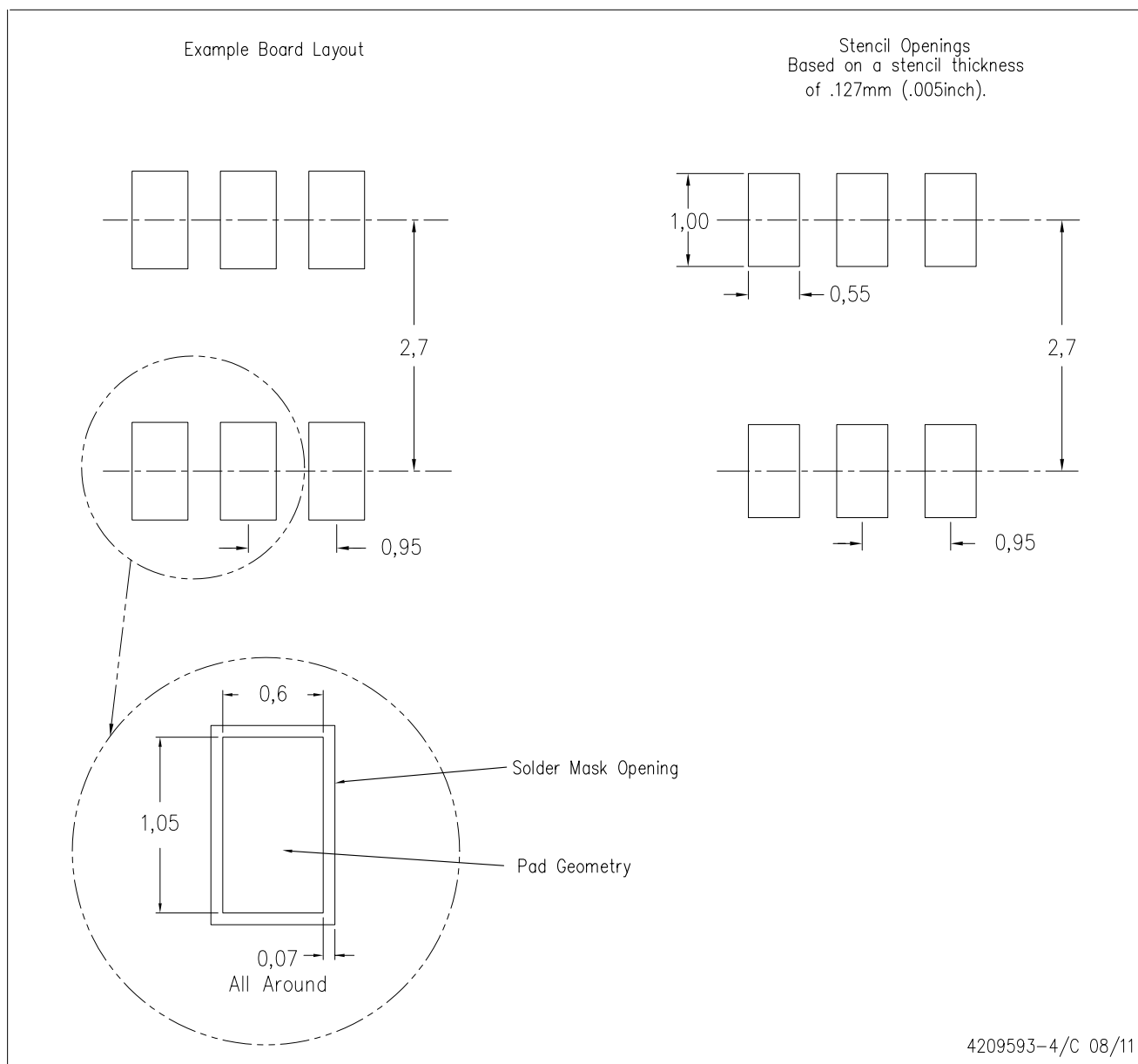


4073253-5/N 12/14

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
  - E. Falls within JEDEC MO-178 Variation AB, except minimum lead width.

DBV (R-PDSO-G6)

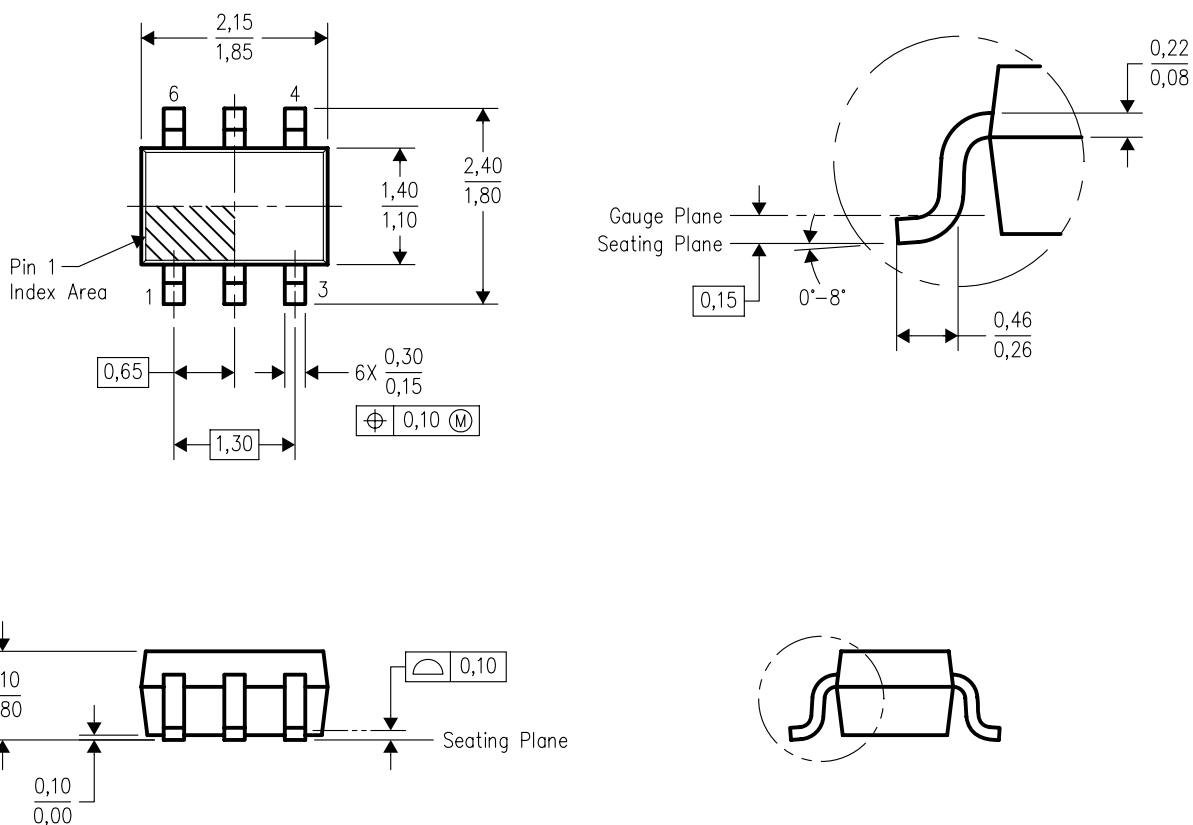
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
  - D. Publication IPC-7351 is recommended for alternate designs.
  - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

## DCK (R-PDSO-G6)

## PLASTIC SMALL-OUTLINE PACKAGE



4093553-4/G 01/2007

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
  - D. Falls within JEDEC MO-203 variation AB.

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|                               |                                                                                          |
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| Computers and Peripherals     | <a href="http://www.ti.com/computers">www.ti.com/computers</a>                           |
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